

# P-Channel Enhancement Mode Power MOSFET

### **Description**

The RM30P30D3 uses advanced trench technology to provide excellent  $R_{\text{DS(ON)}}$ , low gate charge . This device is suitable for use as a load switch or in PWM applications.

#### **General Features**

•  $V_{DS} = -30V, I_{D} = -30A$ 

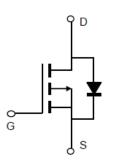
 $R_{DS(ON)}$  < 13m $\Omega$  @  $V_{GS}$ =-4.5V

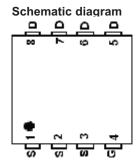
 $R_{DS(ON)}$  < 10m $\Omega$  @  $V_{GS}$ =-10V

- High Power and current handing capability
- Lead free product is acquired
- Surface mount package

### **Application**

- PWM applications
- Load switch
- Power management
- Halogen-free





DFN 3x3 EP top view

### **Package Marking and Ordering Information**

Device Marking Device		Device Package	Reel Size	Tape width	Quantity
30P30	RM30P30D3	DFN3X3	Ø330mm	12mm	2500 units

# Absolute Maximum Ratings (T<sub>A</sub>=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	-30	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	I <sub>D</sub>	-30	А
Drain Current-Pulsed (Note 1)	I <sub>DM</sub>	-90	А
Maximum Power Dissipation	P <sub>D</sub>	40	W
Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	-55 To 150	$^{\circ}$ C

### **Thermal Characteristic**

Thermal Resistance, Junction-to-Case (Note 2) R <sub>BJC</sub> 34 °C/W	
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# Electrical Characteristics (T<sub>A</sub>=25 ℃ unless otherwise noted)

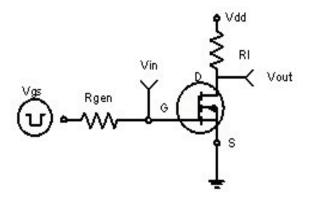
Parameter	Symbol	Condition	Min	Тур	Max	Unit		
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =-250A	-30	-	-	V		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-30V,V <sub>GS</sub> =0V	-	-	-1	μA		
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±12V,V <sub>DS</sub> =0V	-	-	±100	nA		
On Characteristics (Note 3)								
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =-250A	-0.8	-	-2.0	V		
Drain Causes On Ctata Basistanas	-	V <sub>GS</sub> =-10V, I <sub>D</sub> =-15A	-	7	10	mΩ		
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-8A	-	10	13	mΩ		
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> =-10V,I <sub>D</sub> =-5A	-	9	-	S		
Dynamic Characteristics (Note4)								
Input Capacitance	C <sub>lss</sub>	\/ - 25\/\/ -0\/	-	2150	-	PF		
Output Capacitance	Coss	$V_{DS}$ =-25V, $V_{GS}$ =0V, F=1.0MHz	-	430	-	PF		
Reverse Transfer Capacitance	C <sub>rss</sub>	F = 1.0WI112	-	320	-	PF		
Switching Characteristics (Note 4)								
Total Gate Charge	Qg		-	35	-	nC		
Gate-Source Charge	$Q_{gs}$	V <sub>DS</sub> =-15V,I <sub>D</sub> =-15A,V <sub>GS</sub> =-10V	-	5	-	nC		
Gate-Drain Charge	$Q_{gd}$		-	10	-	nC		

### Notes:

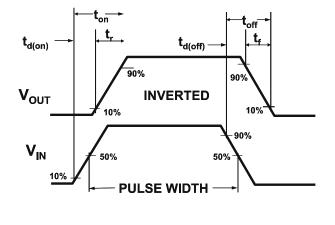
- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production



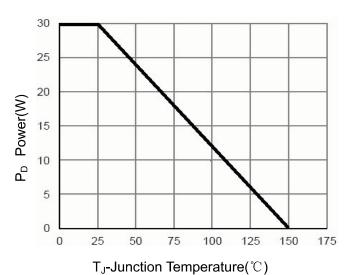
## RATING AND CHARACTERISTICS CURVES (RM30P30D3)



**Figure 1 Switching Test Circuit** 



**Figure 2 Switching Waveforms** 



**Figure 3 Power Dissipation** 

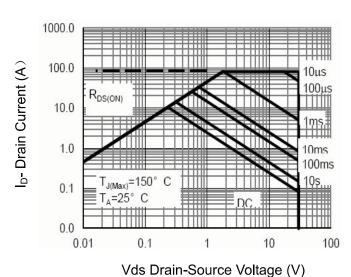
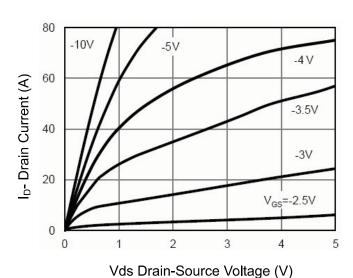


Figure 4 Safe Operation Area



**Figure 5 Output Characteristics** 

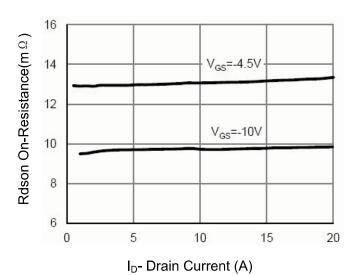
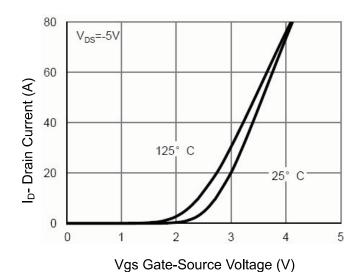


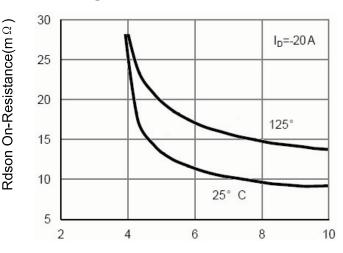
Figure 6 Drain-Source On-Resistance



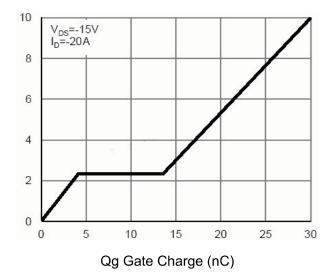
# RATING AND CHARACTERISTICS CURVES (RM30P30D3)



**Figure 7 Transfer Characteristics** 

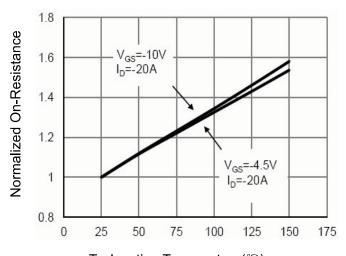


Vgs Gate-Source Voltage (V)
Figure 9 Rdson vs Vgs



Vgs Gate-Source Voltage (V)

Figure 11 Gate Charge



 $\mathsf{T}_{\mathsf{J}} ext{-Junction Temperature}(^{\mathbb{C}})$ 

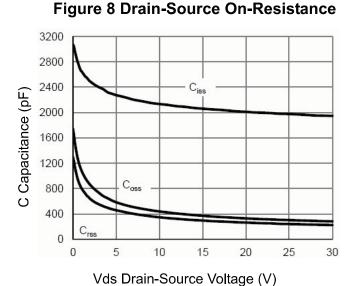


Figure 10 Capacitance vs Vds

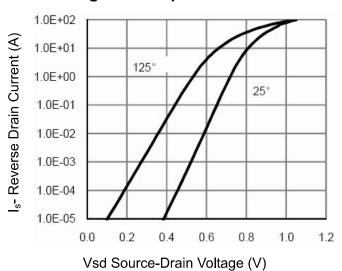
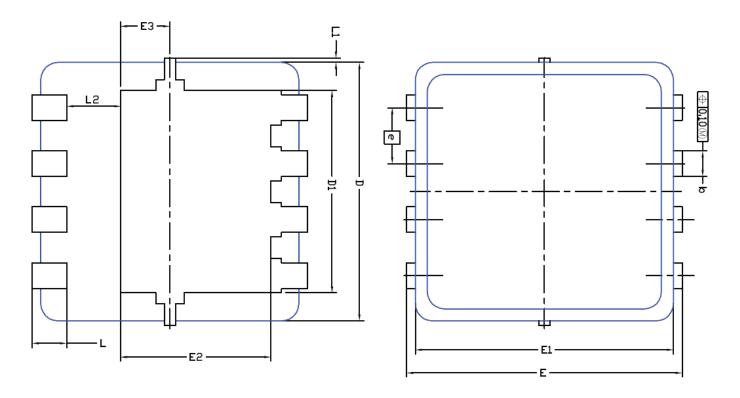
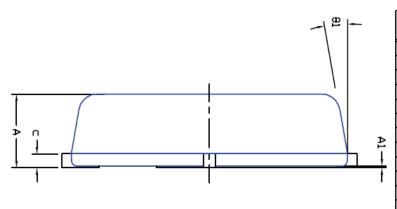


Figure 12 Source- Drain Diode Forward



# **DFN3X3 EP Package Information**





	МТІ	LIMETE	-DC	INCHES			
DIM.	MILLIMETERS						
	MIN	NDM	MAX	MIN	NDM	MAX	
Α	0.700	0.80	0.900	0.0276	0.0315	0.0354	
A1	0.00	i	0.05	0.000	İ	0.002	
σ	0,24	0,30	0,35	0,009	0.012	0.014	
n	0,10	0,152	0,25	0,004	0,006	0,010	
D	3.00 BSC			0.118 BSC			
D1	2.35 BSC			0.093 BSC			
Ε	3.20 BSC			0.126 BSC			
E1	3,00 B2C			0.118 BSC			
E2	1,75 BSC			0.069 BSC			
E3	0.575 BSC			0.023 B2C			
е	0.65 BSC			0.026 BSC			
L2	0.685BSC			0.0274 BSC			
L	0.30	0.40	0,50	0.0118 0.0157		0.0197	
L1	0		0.100	0		0.004	
θ1	0°	10°	12°	0°	10°	12°	



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